

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Nishant Sinha

**Serial No.:** 10/668,914

**Filed:** September 23, 2003

**For:** PROCESS AND INTEGRATION  
SCHEME FOR FABRICATING  
CONDUCTIVE COMPONENTS,  
THROUGH-VIAS AND  
SEMICONDUCTOR COMPONENTS  
INCLUDING CONDUCTIVE THROUGH-  
WAFER VIAS

**Confirmation No.:** 2525

**Examiner:** W. Lindsay Jr.

**Group Art Unit:** 2812

**Attorney Docket No.:** 2269-5859US  
(02-0390.00/US)

**Notice of Allowance Mailed:**

March 22, 2007

**VIA ELECTRONIC FILING  
JUNE 20, 2007**

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the specification** begin on page 3 of this paper;

**Amendments to the claims** are set forth in the listing of the claims that begins on page 5 of this paper; and

**Remarks** start at page 8 of this paper.